



Product Change Notification

110662 - 00

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Should you have any issues with the timeline or content of this change, please contact the Intel Representative(s) for your geographic location listed below. No response from customers will be deemed as acceptance of the change and the change will be implemented pursuant to the key milestones set forth in this attached PCN.

Americas Contact: asmo.pcn@intel.com

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Product Change Notification

Change Notification #: 110662 - 00
Change Title: Intel® Desktop Board DP67DE, Boxed and Bulk
PCN 110662-00, Product Design
Hardware Support Added for Future Processors
Date of Publication: May 27, 2011

Key Characteristics of the Change:

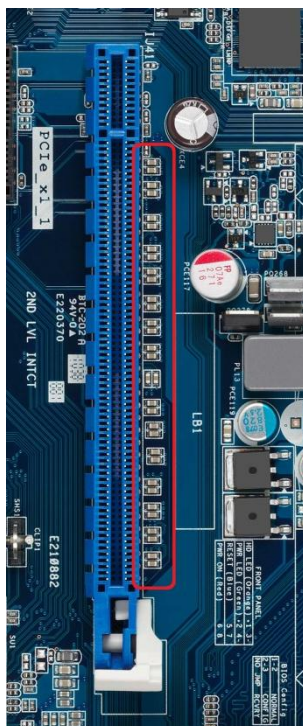
Product Design

Forecasted Key Milestones:

Date Customer Must be Ready to Receive Post-Conversion Material:	Jun 13, 2011
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Description of Change to the Customer:

Change the PCIe x16 slot AC decoupling capacitor values from 100nF to 220nF. The capacitor location designators are from XC1 to XC32. You may also refer to the location in the picture below.



Customer Impact of Change and Recommended Action:

This change has been thoroughly evaluated to ensure that there are no quality, reliability or functional implications to our customers. Intel is not recommending additional qualification of these changes on platforms received from Intel.

Intel will attempt to deplete pre-conversion material before shipping post-conversion material but there is a possibility of Intel shipping mixed inventory. Therefore, customers will need to manage and migrate to the post-conversion material as soon as possible.

Milestone dates are estimates and subject to change based on business and operational conditions.

Products Affected / Intel Ordering Codes:

Product Code	MM#	Pre Change AA	Post Change AA
BOXDP67DEB3	915083	G10217-300	G10217-301
BLKDP67DEB3	915084	G10217-300	G10217-301

PCN Revision History:

Date of Revision:

May 27, 2011

Revision Number:

00

Reason:

Originally Published PCN